

SUPPLEMENTAL MATERIAL

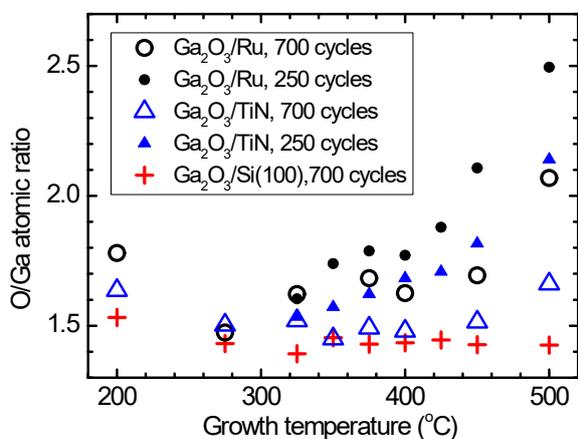


Fig. S1. O/Ga atomic ratios determined by XRF for samples with Ga₂O₃ films deposited at 200–500 °C on uncoated Si(100) and on substrates with Ru and TiN bottom electrodes. The O/Ga atomic ratio depends on the content of these elements in the whole Ga₂O₃/Ru/Si, Ga₂O₃/TiN/Si, and Ga₂O₃/Si stacks. According to STEM results (Fig. 1), oxidation of Ru and TiN has a marked effect on the O/Ga ratio determined by XRF, particularly, in the case of samples with thinner Ga₂O₃ films.

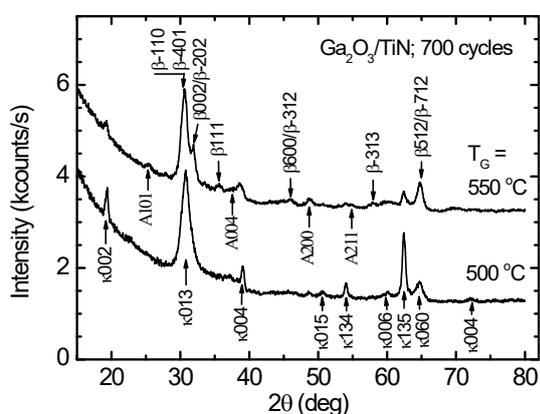


Fig. S2. GIXRD diffractogram of samples with Ga₂O₃ films deposited at 500 and 550 °C on a TiN bottom electrode by using 700 ALD cycles. The growth temperatures and thicknesses of films are shown at corresponding diffractograms. Miller indices of κ-Ga₂O₃ (κ), β-Ga₂O₃ (β), and anatase-phase TiO₂ (A) are shown at respective reflections.

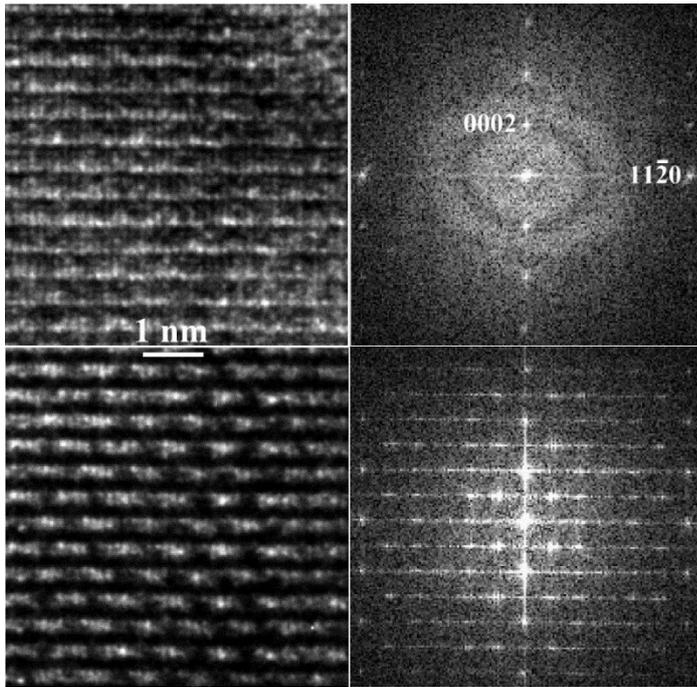


Fig. S5. (a, c) Enlarged high resolution images and (b, d) corresponding FFT from Fig. 4 for (a,b) ϵ -Ga₂O₃ and (c, d) κ -Ga₂O₃.

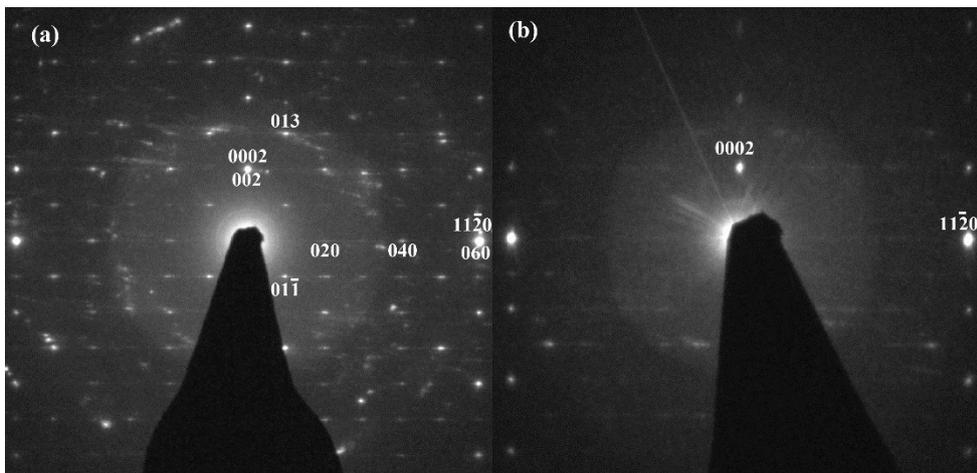


Fig. S6 SAED patterns from (a) κ -Ga₂O₃ and (b) ϵ -Ga₂O₃. Selected reflections are labelled using four- (ϵ -Ga₂O₃) or three-index (κ -Ga₂O₃) notations.

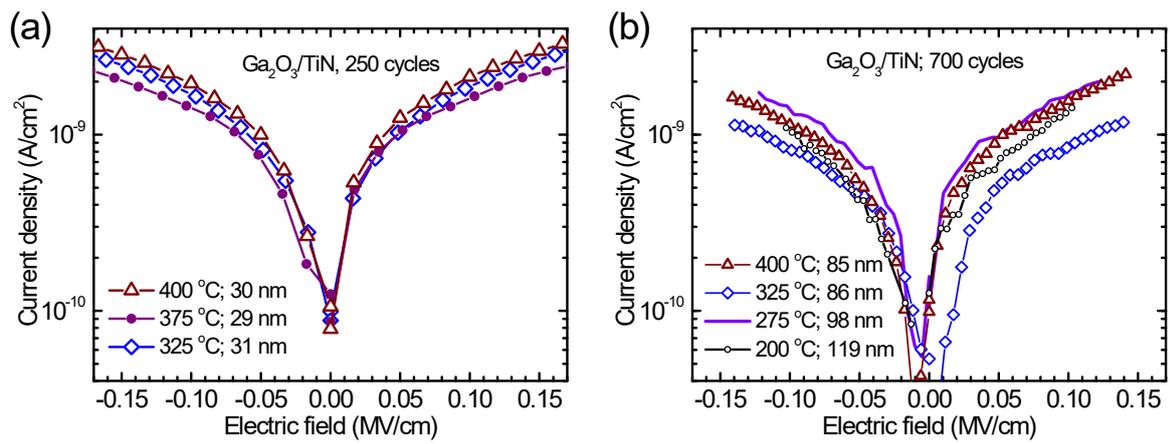


Fig. S7. Current density recorded as a function of electric field strength for Ga_2O_3 films deposited on TiN at different temperatures using (a) 250 and (b) 700 ALD cycles. The deposition temperatures and film thicknesses are depicted in the figure panels.